

1.(Currently amended) A process for manufacturing a wiring board, said process comprising the following steps of:

making a resin plate which has wiring pattern recesses with inner walls therein and via through holes using a pair of molds;

coating all of the surfaces of the resin plate including said inner walls of said wiring pattern recesses and said via through holes with a metal film;

electro-plating using said metal film as a power-supply layer over an entire surface of said metal film so as to fill a plated metal into said wiring pattern recesses and into said via through holes; and

polishing said electro-plated metal formed on said resin plate to remove the same except for said inner walls inside regions of said wiring pattern recesses and said via through holes, to yield a wiring pattern and vias, so that said plated metal wiring pattern recesses and said plated metal vias which are exposed on a surface that is the same as that of said resin plate.

2.(Currently amended) A process as set forth in claim 1, wherein said resin plate is made formed by a press-forming process using a pair of press-forming molds.

3.(Currently amended) A process as set forth in claim 1, wherein said resin plate is made formed by an injection molding process using a pair of injection molds.

4.(Currently amended) A process as set forth in claim 1 further comprising the following step s- of:

forming pads as a part of said wiring pattern formed from said exposed plated metal recesses on one surface of the resin plate to which external connecting terminals are to be attached.

5.(Currently amended) A process as set forth in claim 1 further comprising the following steps of:

using said wiring board as a core substrate;
forming a resin layer on said core substrate; and
forming a wiring pattern on said resin layer in such a manner that said wiring pattern is connected to a said wiring pattern formed from said wiring pattern recesses or to said vias of said core substrate.

6.(Currently amended) A process for manufacturing a multi-layer wiring board, said process comprising:

(a) manufacturing a core substrate comprising the steps of:
making a resin plate having wiring pattern recesses with inner walls therein and having via through holes using a pair of molds;
coating all of the surfaces of the resin plate including said inner walls of said wiring pattern recesses and said via through holes with a metal film;
electro-plating using said metal film as a power-supply layer over an entire surface of said metal film to fill a plated metal into said wiring pattern recesses and into said via through holes; and

polishing said plated metal formed on said resin plate to remove the same except for the inner walls inside regions of said wiring pattern recesses and of said via through holes to yield a wiring pattern and vias, so that wiring pattern and vias which are exposed on a surface that is the same as that of said resin plate; and

(b) forming resin layers on respective surfaces of said core substrate so that said respective resin layers include[[s]] wiring pattern recesses having inner wall thereof and include via through holes;

(c) coating all of the surfaces of said respective resin layers including said inner walls of said wiring pattern recesses and said via through holes with a metal film;

(d) applying an electro-plating using said metal film as a power-supply layer over an entire surface of said metal film to fill a plated metal into said wiring pattern recesses and into said via through holes; and

(e) polishing said plated metal formed on each of said respective resin layers to remove the same except for the inner walls inside regions of said wiring pattern recesses and said via through holes to yield a wiring pattern and vias, so that wiring pattern and vias which are exposed on at a surface which is the same as that of the respective said resin layer.

7.(Currently amended) A process as set forth in claim 6, wherein said resin plate is formed made by a press-forming process using a press-forming mold.

8.(Currently amended) A process as set forth in claim 6, wherein said resin plate is made formed by a injection molding process using an injection mold.

9.(Currently amended) A process for manufacturing a ~~multi-layer~~ wiring board comprising the following steps of:

- (a) preparing a laminated body comprising at least one resin layer and at least one wiring ~~layer~~ laminated pattern on said resin layer;
- (b) forming said resin layer with wiring pattern recesses having inner walls and with via through holes using a mold;
- (c) coating all of the surfaces of the resin layer including said inner walls of said wiring pattern recesses and said via through holes with a metal film;
- (d) electro-plating using said metal film as a power supply layer over an entire surface of said metal film so as to fill a plated metal into said wiring pattern recesses and said via through holes; and
- (e) polishing said plated metal formed on said resin layer to remove the same except for the inner walls inside regions of said wiring pattern recesses and said via through holes to yield a wiring pattern and vias, so that said wiring pattern and said vias are exposed on a surface which is the same as the surface that of said resin layer.

10.(Previously presented) A process as set forth in claim 9, wherein said resin layer is formed by press-forming process using a press-forming mold.

11.(Previously presented) A process as set forth in claim 9, wherein said resin layer is formed injection molding process using an injection mold.

12.(Currently amended) A process for manufacturing a multi-layer wiring board comprising the following steps of:

- (a) preparing a multi-layer wiring board which is made in accordance with the steps as defined in claims 9;
- (b) forming a second resin layer with wiring pattern recesses and with via through holes using a mold on said wiring board, said wiring pattern recesses having inner walls;
- (c) coating all of the surfaces of the second resin layer including said inner walls of said wiring pattern recesses and said via through holes with a metal film;
- (d) electro-plating using said metal film as a power supply layer over an entire surface of said metal film so as to fill a plated metal into said wiring pattern recesses and said via through holes; and
- (e) polishing said plated metal film formed on said second resin layer to remove the same except for the inner walls inside regions of said wiring pattern recesses and said via through holes to yield a wiring pattern and vias, so that said wiring pattern and said vias are exposed on a surface that is the same as that of said second resin layer.

13.(Amended) A process as set forth in claim 12 further comprising the following steps of:

repeating said steps (b) to (e) to obtain a multi-layer wiring board comprising a third an even further or subsequent resin layer(s) formed on the resin layer.

14.(Amended) A process for manufacturing a wiring board, said process comprising the following steps of:

molding a resin plate to form wiring pattern recesses and via through holes in on said resin plate, said wiring pattern recesses having inner walls;

coating all of the surfaces of the resin plate including said inner walls of said wiring pattern recesses and said via through holes with a metal film;

electro-plating using said metal film as a power supply layer over an entire surface of said metal film so as to fill a plated metal into said wiring pattern recesses and said via through holes; and

polishing said plated metal formed on said resin plate to remove the same except for the inner walls inside regions of said wiring pattern recesses and said via through holes, so that to yield a wiring pattern and vias which are exposed on a surface that is the same as that of said resin plate.